

# **ReMov**<sup>™</sup> Board-Level Shield with Detachable Pickup Bridge

Innovative **Technology** for a **Connected** World



## **BOARD-LEVEL SHIELD SETS STANDARD FOR DETACHABLE PICKUP BRIDGE**

The ReMovl<sup>™</sup> brand board-level shield incorporates the ReCovr attachment mechanism applied to the pickup bridge of a BLS frame to allow for easy, tool-less detachment of the bridge after the frame is soldered to the PCB. Ease of detachment along with reliable and consistent separation force will allow for automated detachment.

#### **Raised Pickup Bridge**

Taking this technology one step further, Laird Technologies has developed a raised ReMovl<sup>™</sup> pickup bridge option which allows for clearance above PCB components during placement and reflow. See Figure 1

This feature provides overall reduction in final Z height since the frame height after bridge detachment no longer needs to account for the component heights prior to reflow. (Difference between PCB component placement height before and after solder reflow.) See Figure 2

#### **FEATURES**

- Detachment is permanent cannot be replaced like the pickup bridge in Laird Technologies' ReCovr<sup>™</sup> product.
- Min. height: 2.0 mm (.080") lower heights require product development review
- Top flange width: 1.8 mm (.071")
- Flatness: Part size dependent, but typical to other frame BLS parts
- Configurations min. 4 legs/branches required (see BLS style options)
- Limitations: Must be folded or rigid corner type BLS (No fully drawn parts.)
- Pull Force (Typ) 0.5 1.0 lbs

## **MARKETS OR APPLICATIONS**

- Ideal for customer manufacturing processes where post reflow detachment of the pickup bridge is required or desired. Applications that often require the pickup bridge to be detached include:
  - Inspection
  - Rework
  - Thermal Interface Material or Absorber into cover
  - Cover with contact fingers to chip, etc.
  - Noise / Vibration concerns of bridge to cover

**Note:** Due to delicate nature of the attachment of the pickup bridge, there will be some risk to the bridge separating during pick and place operations depending on customer manufacturing processes. Pick and place head depth tolerance (z axis) -.020"



## global solutions: local support

USA: +1.866.928.8181 Europe: +49.0.8031.2460.0 Asia: +86.755.2714.1166

# Figure 2: Reduction in height of BLS Frame due to Raised $\operatorname{ReMovI}^{\text{\tiny TM}}$ Pickup Bridge

#### EMI-DS-REMOVL 0612

Any information furnished by Laird Technologies, Inc. and its agents is believed to be accurate and reliable. All specifications are subject to change without notice. Responsibility for the use and application of Laird Technologies materials rests with the end user, since Laird Technologies and its agents cannot be aware of all potential uses. Laird Technologies makes no warranties as to the fitness, merchantability or suitability of any Laird Technologies materials or products for any specific or general uses. Laird Technologies shall not be laiked for incidental or consequential damages of any kind. All Laird Technologies products are sold pursuant to the Laird Technologies 'Terms and Conditions of sale in effect from time to time a cony of which will be furnished upon request. © Copyright 2012 Laird Technologies, Rights Reserved. Laird, Laird Technologies, the Laird Technologies to go, and other marks or tradies damarks or laird technologies and Technologies. Note and the property of third parties. Nothing herein provides a license under any Laird Technologies or any third party intellectual property rights.

www.lairdtech.com